

Sensors and Materials

Special Issue on Appropriate Applied Sciences, Technologies, and Engineering based on Sensors and Materials for New Normal Era

Call for Papers

The Covid-19 pandemic has changed the landscape of work and lifestyles. As office reopen, online and on-site jobs have been hybridized. Technology is playing a crucial role in this new normal. To prepare for the new normal, government agencies, academia, and industry have redirected investments to new technological solutions to facilitate resilient, safe, and healthy work environments. This special issue will focus on appropriate technologies and new trends and solutions to assist people to work and restart the economy in an effective way. Submitted papers must be related to the sensors, materials, and methods presented in the scope but are not limited to the examples in the list.

Scope:

- Robotics and AI
- Medical materials
- Energy, food, and chemical sensing devices
- Metaverse-related devices

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Guest Editor: Prof. Pitikhate Sooraksa (King Mongkut's Institute of Technology Ladkrabang)

Submit to: Online Manuscript Submission System (<https://myukk-org.ssl-xserver.jp/form/>)

(Attention)

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon the acceptance of the manuscript for publication (for example, JPY 112200 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors should bear the proofreading fee (JPY 10000-40000), which will be charged with the publication fee.

If you have any questions, please feel free to contact the editorial staff at the address below.

Editorial Department of *Sensors and Materials*

MYU K.K.

1-23-3-303 Sendagi, Bunkyo-ku, Tokyo 113-0022, Japan

Tel: +81-3-3827-8549, Fax: +81-3-3827-8547

E-mail: myukk@myu-inc.jp

